

1. General description

Ultrafast power diode in a SMB surface-mountable plastic package.

2. Features and benefits

- Low on-state loss
- Low leakage current
- Low thermal resistance
- Surface-mountable package
- Reduces switching losses in associated MOSFET or IGBT

3. Applications

- Buck and Boost converter
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)
- Inverter freewheeling and protection diode

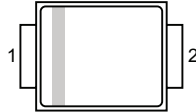

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute maximum rating						
V_{RRM}	repetitive peak reverse voltage		600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{lead} \leq 105\text{ }^{\circ}\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	3			A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{lead} \leq 105\text{ }^{\circ}\text{C}$; square-wave pulse	6			A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse; Fig. 4	100			A
		$t_p = 8.3\text{ ms}$; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse;	110			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward voltage	$I_F = 3\text{ A}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 6	-	-	1.3	V
		$I_F = 3\text{ A}$; $T_j = 150\text{ }^{\circ}\text{C}$; Fig. 6	-	0.88	1.05	V
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1\text{ A}$; $V_R = 30\text{ V}$; $di_F/dt = 50\text{ A}/\mu\text{s}$; $T_j = 25\text{ }^{\circ}\text{C}$; Fig. 7	-	50	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
MURS360B	SMB	MURS360BJ	Reel	3000	SMB	20-Feb-2017

7. Marking

Table 4. Marking codes

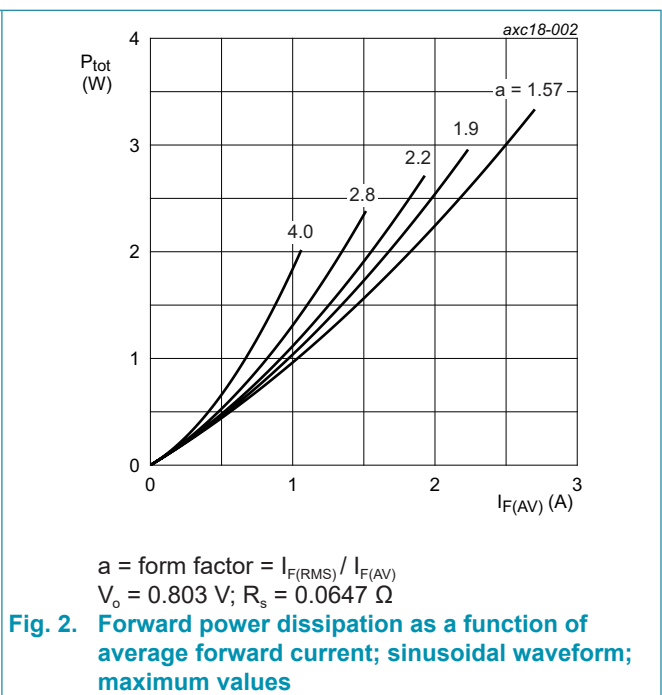
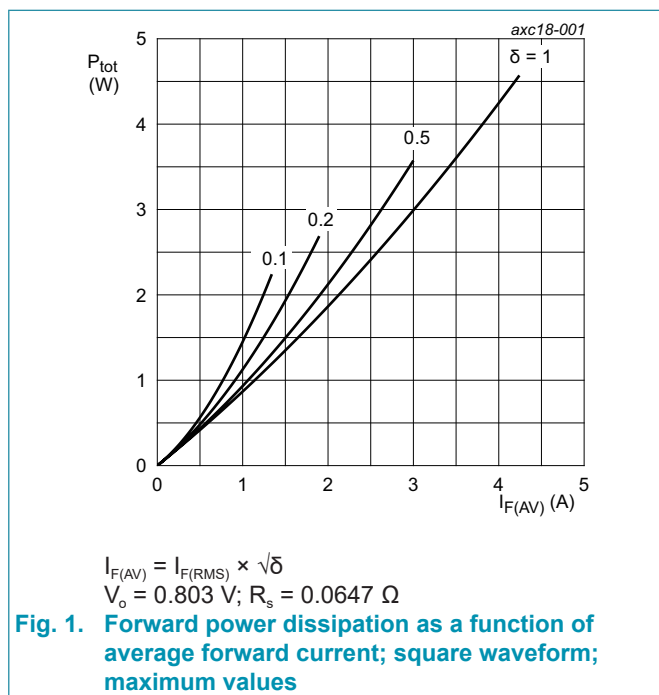
Type number	Marking codes
MURS360B	360B

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{lead} \leq 105\text{ }^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	3	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{lead} \leq 105\text{ }^\circ\text{C}$; square-wave pulse	6	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(init)} = 25\text{ }^\circ\text{C}$; sine-wave pulse; Fig. 4	100	A
		$t_p = 8.3\text{ ms}$; $T_{j(init)} = 25\text{ }^\circ\text{C}$; sine-wave pulse;	110	A
T_{stg}	storage temperature		-65 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



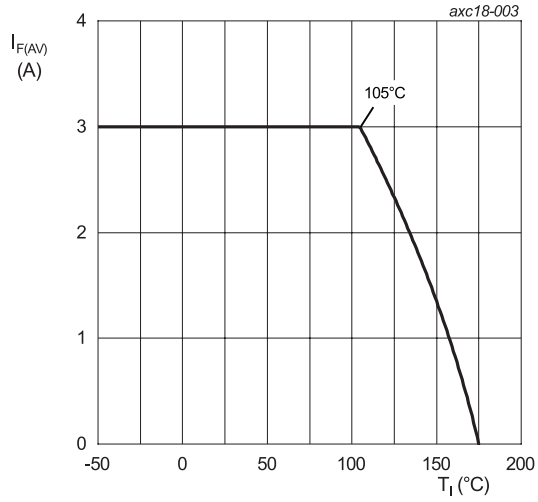


Fig. 3. Forward current as a function of lead temperature; typical values

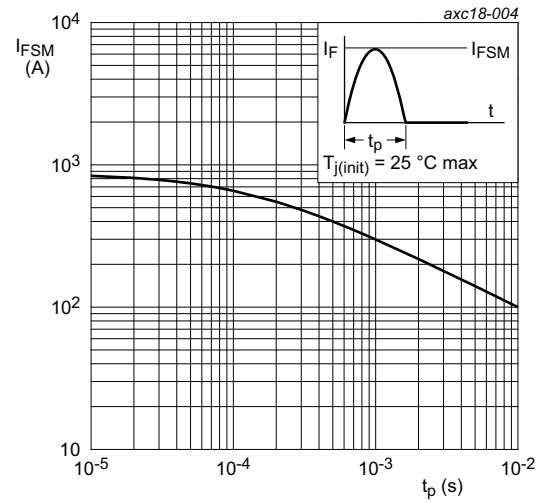


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-lead)}$	thermal resistance from junction to lead	mounted on a minimum footprint printed-circuit board (FR4); Fig. 5	-	23	25	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	mounted on a minimum footprint printed-circuit board (FR4)	-	75	-	K/W

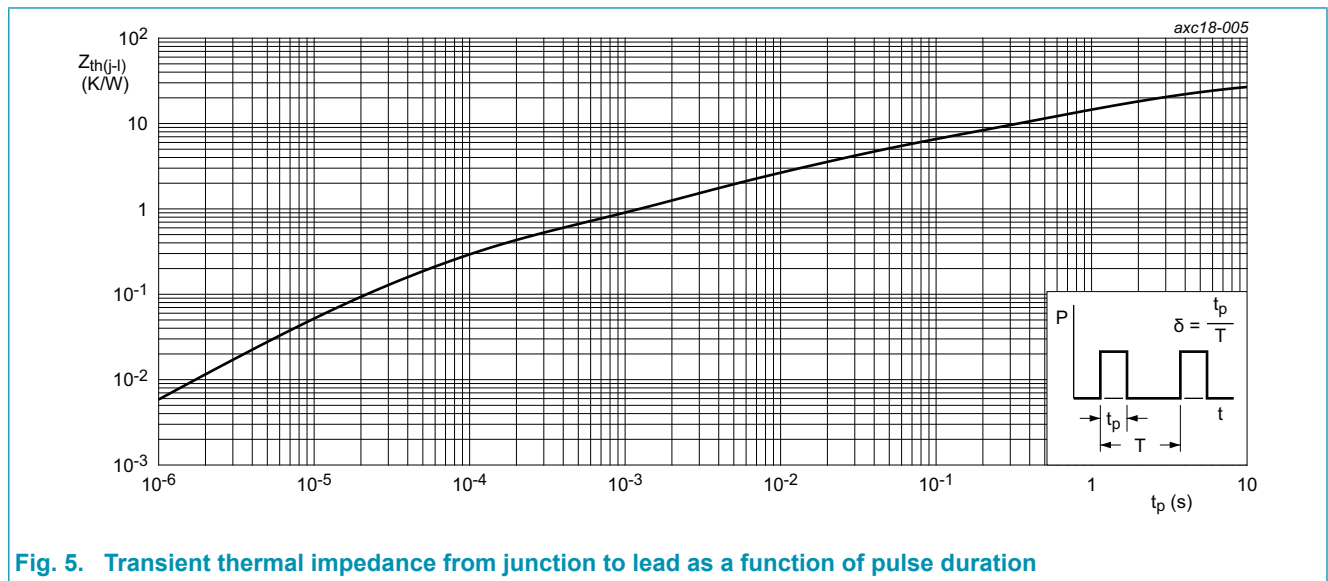
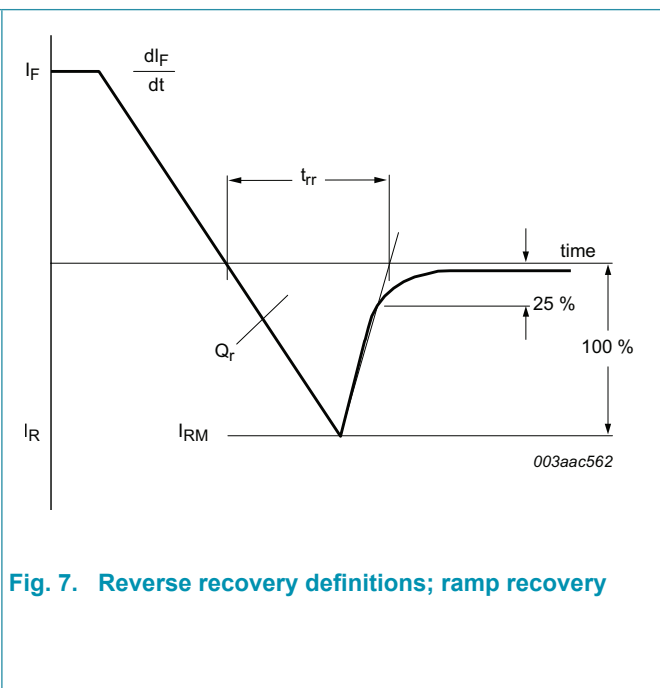
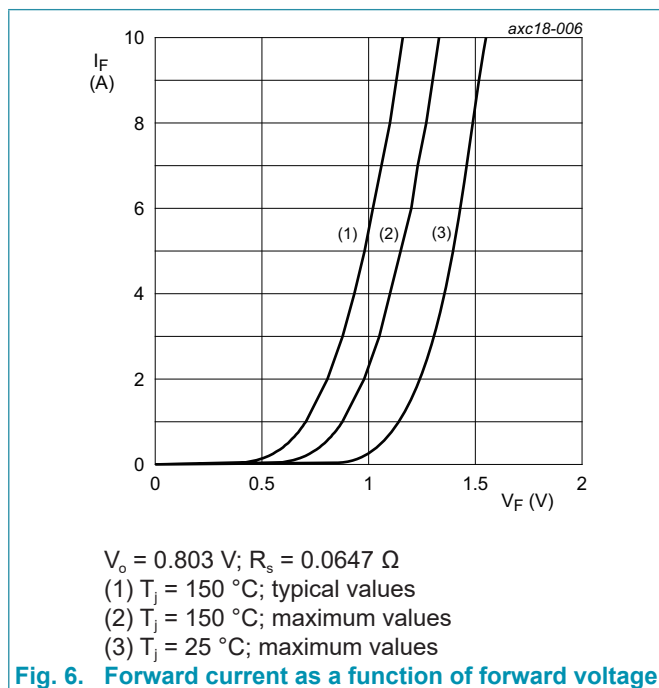


Fig. 5. Transient thermal impedance from junction to lead as a function of pulse duration

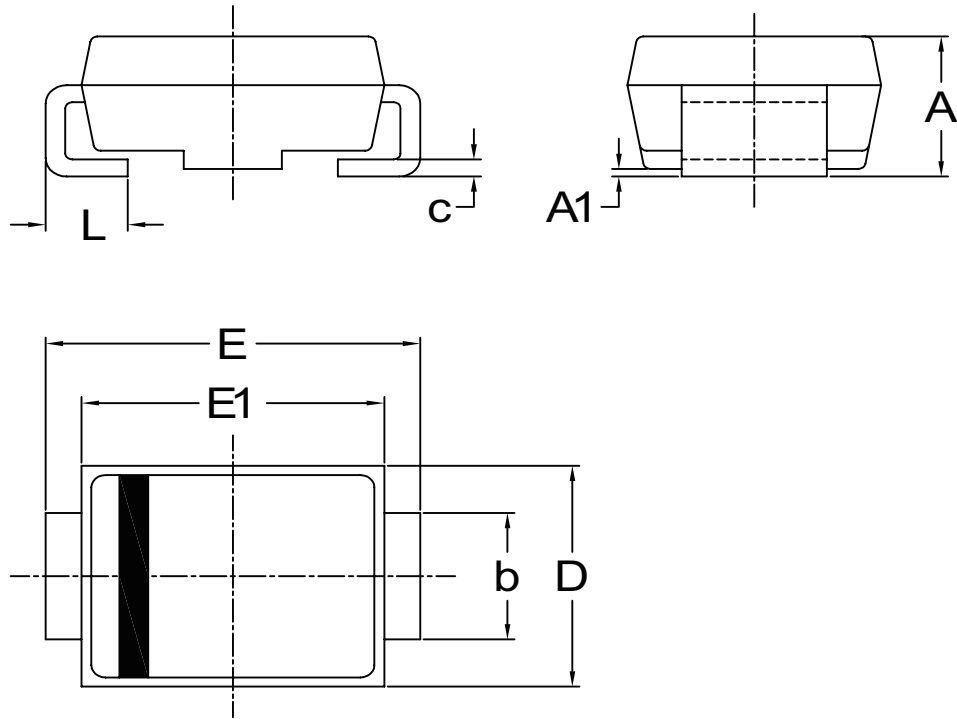
10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward current	$I_F = 3\text{ A}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 6}$	-	-	1.3	V
		$I_F = 3\text{ A}; T_j = 150\text{ }^\circ\text{C}; \text{Fig. 6}$	-	0.88	1.05	V
I_R	reverse current	$V_R = 600\text{ V}; T_j = 25\text{ }^\circ\text{C}$	-	-	3	μA
		$V_R = 600\text{ V}; T_j = 150\text{ }^\circ\text{C}$	-	-	1	mA
Dynamic characteristics						
Q_r	reverse charge	$I_F = 3\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 7}$	-	122	-	nC
		$I_F = 3\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}; \text{Fig. 7}$	-	199	-	nC
t_{rr}	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; dI_F/dt = 50\text{ A}/\mu\text{s}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 7}$	-	50	-	ns
		$I_F = 0.5\text{ A}; I_R = 1\text{ A}; I_{R(\text{meas})} = 0.25\text{ A}; T_j = 25\text{ }^\circ\text{C}; \text{Step recovery}$	-	-	50	ns
		$I_F = 3\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 7}$	-	52	-	ns
		$I_F = 3\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}; \text{Fig. 7}$	-	65	-	ns
I_{RM}	peak reverse recovery current	$I_F = 3\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 25\text{ }^\circ\text{C}; \text{Fig. 7}$	-	4.7	-	A
		$I_F = 3\text{ A}; V_R = 400\text{ V}; dI_F/dt = 200\text{ A}/\mu\text{s}; T_j = 125\text{ }^\circ\text{C}; \text{Fig. 7}$	-	6.1	-	A
E_{as}	non-repetitive avalanche energy	$I_R = 1.2\text{ A}; T_{j(\text{init})} = 25\text{ }^\circ\text{C}; L = 15\text{ mH}$	10.8	-	-	mJ



11. Package outline



UNIT	A	A1	b	c	D	E	E1	L	
mm	Max	2.50	0.20	2.21	0.31	3.95	5.60	4.60	1.60
	Min	2.00	0.05	1.96	0.15	3.30	5.20	4.05	0.75

Remark: Dimensions D and E1 do not include mold flash.

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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Date of release: 30 December 2019

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